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(21) International Application Number: PCT/US98/05085 (22) International Filing Date: 17 March 1998 (17.03.98) (30) Priority Data: 60/041,402 19 March 1997 (19.03.97) US (71) Applicant: JOHNSON MATTHEY ELECTRONICS, INC. [US/US]; East 15128 Euclid Avenue, Spokane, WA 99216 (US). (72) Inventors: SHAH, Ritesh, P.; 23415 East Desmet Court, Liberty Lake, WA 99019 (US). STEELE, David, E.; East 1923 5th Avenue, Spokane, WA 99202-3305 (US). TURNER, William, R.; North 1711 Walnut, Spokane, WA 99206 (US). BEIER, Anthony, F.; 13518 East 29th Street, Spokane, WA 99216 (US). KARDOKUS, Janine, K.; East 1822 Monte Vista Court, Otis Orchards, WA 99027 (US). STROTHERS, Susan, D.; North 12426 Forker Road, Spokane, WA 99207 (US). (74) Agent: GIOIA, Vincent, G.; Christie, Parker & Hale, LLP, P.O. Box 7068, Pasadena, CA 91109-7068 (US).		(81) Designated States: CN, JP, KR, SG, European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report.</i>
(54) Title: NI-PLATED TARGET DIFFUSION BONDED TO A BACKING PLATE AND METHOD OF MAKING SAME (57) Abstract Described is a method of making a heat treated sputtering target and a sputtering target assembly with a precipitation hardened backing plate diffusion hardened to a sputtering target.		